



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-03-31
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KD6P*1021ABY	A	BO2A	2014-03-31
Amount	UoM	Unit type	ST ECOPACK Grade	
34.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used on	Nickel/Palladium/Gold (Ni/Pd/Au/Ag)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.4X3.0X0.9	5	gull wing	
Comment	Package: TSSOP 8 BODY 4.4 PITCH 0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KD6P*1021ABY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.52	mg	supplier	die	Silicon (Si)	7440-21-3		1.461	mg	961184	42971
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	9868	441
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1316	59
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	2632	118
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.025	mg	16447	735
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.009	mg	5921	265
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.004	mg	2632	118
Leadframe	Copper & its alloys	15.734	mg	supplier	alloy	Copper (Cu)	7440-50-8		15.048	mg	956400	442588
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.469	mg	29808	13794
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.023	mg	1462	676
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.102	mg	6483	3000
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	5275	2441
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	191	88
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	191	88
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.003	mg	191	88
Die attach	Other Organic Materials	0.557	mg	supplier	glue	Silver (Ag)	7440-22-4		0.507	mg	910233	14912
Die attach				supplier	acrylate	Proprietary			0.028	mg	50269	824
Die attach				supplier	glue	Methacrylate	Proprietary		0.022	mg	39497	647
Bonding wire	Other inorganic materials	0.018	mg	supplier	wire	Copper (Cu)	7440-50-8		0.018	mg	1000000	529
encapsulation	Other Organic Materials	16.171	mg	supplier	mold compound	Silica, vitreous	60676-86-0		14.181	mg	876940	417088
encapsulation				supplier	mold compound	Epoxy resin A	EC 413-900-7		0.647	mg	40010	19029
encapsulation				supplier	mold compound	Epoxy resin B	29690-82-2		0.647	mg	40010	19029
encapsulation				supplier	mold compound	phenol resin	Proprietary		0.485	mg	29992	14265
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.049	mg	3030	1441
encapsulation				supplier	mold compound	additive	Proprietary		0.162	mg	10018	4765